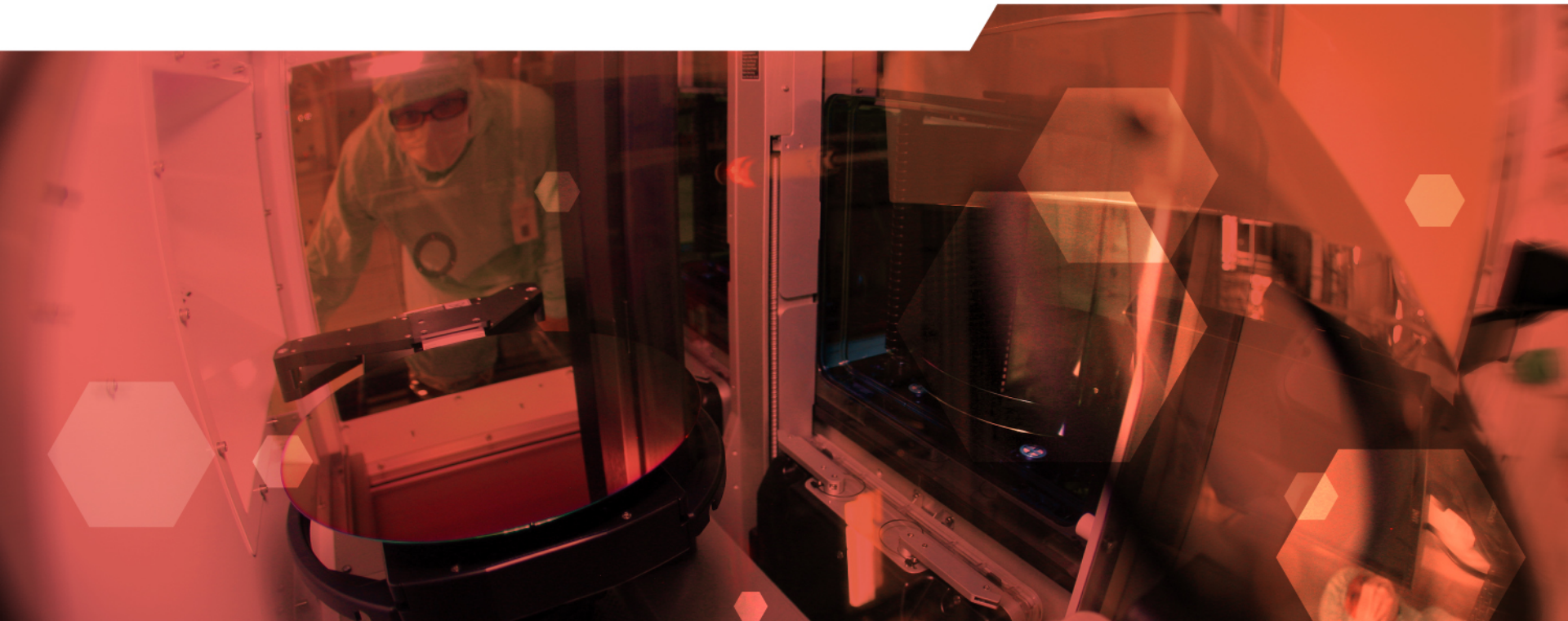


Japan TC Chapter Physical Interfaces & Carriers (PI&C) Global Technical Committee

Liaison Report

July, 2019

V1.0



Meeting Information

- Last meeting
 - April 18 at the Japan Standards Spring 2019 Meetings
 - SEMI Japan office, Tokyo, Japan
- Next meeting
 - September 20 at the Japan Standards Fall 2019 Meetings
 - SEMI Japan office, Tokyo, Japan

<http://www1.semi.org/en/standards-events>

Leadership

Co-chairs

- Committee Co-chairs
 - Tsuyoshi Nagashima (Miraial)
 - GCS voting member
 - PI&C Committee representative to the JRSC
 - Kenji Yamagata (DAIFUKU)
 - GCS voting member
 - Noriyoshi Toyoda (Hirata Corporation)
- Technical Architect
 - Shoji Komatsu (Acteon NEXT)

Leadership Changes

<i>TF/SC/CFG/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
300mm Tape Frame PI&C Task Force	<p>The following person stepped down from TF leader</p> <ul style="list-style-type: none">• Masayuki Azuma (Tokyo Seimitsu)	<p>The following persons remains as TF leaders</p> <ul style="list-style-type: none">• Hayato Iwamoto (Sony Semiconductor Solutions)• Hisashi Goto (Sony Semiconductor Solutions)• Naomune Taniguchi (Tokyo Seimitsu).

Organization Chart

Japan TC Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Tsuyoshi Nagashima (Miraial)
C: Kenji Yamagata (Daifuku)
C: Noriyoshi Toyoda (Hirata Corporation)

Technical Architect

Shoji Komatsu / Acteon NEXT

300 mm Tape Frame PI&C TF

Hayato Iwamoto (Sony Semiconductor Solutions)
Hisashi Gotoh (Sony Semiconductor Solutions)
Naomune Taniguchi (Tokyo Seimitsu)
Masayuki Azuma (Tokyo Seimitsu)

Stepped down

Panel Level Packaging (PLP) Panel FOUP TF

Shoji Komatsu (Acteon NEXT)
John Rudolf (Intel)

Japan Electron Microscopy Workflow liaison TF

Kyoichiro Asayama (JEOL)
Tsuyoshi Onishi (Hitachi High-Technologies)

Global PIC Maintenance TF

Larry Hartsough (U.A. Associates)
Shoji Komatsu (Acteon NEXT)

International Activities

JA Shipping Box TF

Tsuyoshi Nagashima (Mirial)
Shoji Komatsu (Acteon NEXT)

International 450mm Shipping Box TF

Tom Quinn (Intel)
Shoji Komatsu (Acteon NEXT)

Under Silicon Wafer Japan TC Chapter

Activities Approved via GCS between Meetings

#	Type	SC/TF/WG	Title/Details
6485	SNARF Revision	PLP Panel FOUP TF	New Standard - SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING – <i>GCS approved revision SNARF and authorized for ballot on June 25</i> – <i>Balloted in Voting Cycle 6-2019</i>
6486	SNARF Revision	PLP Panel FOUP TF	New Standard - SPECIFICATION FOR PANEL FOUP LOADPORT FOR PANEL LEVEL PACKAGING – <i>GCS approved revision SNARF and authorized for ballot on June 25</i> – <i>Balloted in Voting Cycle 6-2019</i>

Authorized Activities - 1/2

Doc #	Type	SC/TF/CFG	Document Title/Details
6520	SNARF	300mm Tape Frame PI&C TF	New Standard - SPECIFICATION FOR 300mm TAPE FRAME FOUP – Authorized new SNARF – TC Member Review took place between 4/3/2019 and 4/16/2019 before approval at the TC Chapter Meeting
6521	SNARF	300mm Tape Frame PI&C TF	New Standard - SPECIFICATION FOR 300mm TAPE FRAME FOUP LOAD PORT – Authorized new SNARF – TC Member Review took place between 4/3/2019 and 4/16/2019 before approval at the TC Chapter Meeting
6522	SNARF	300mm Tape Frame PI&C TF	New Standard - SPECIFICATION FOR FRONT OPENING INTERFACE BETWEEN 300mm TAPE FRAME FOUP AND LOAD PORT – Authorized new SNARF – TC Member Review took place between 4/3/2019 and 4/16/2019 before approval at the TC Chapter Meeting

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Authorized Activities – 2/2

Doc #	Type	SC/TF/CFG	Document Title/Details
6523	SNARF	300mm Tape Frame PI&C TF	New Standard - SPECIFICATION FOR BOLTS OF 300mm TAPE FRAME FOUP LOAD PORT – Authorized new SNARF – TC Member Review took place between 4/3/2019 and 4/16/2019 before approval at the TC Chapter Meeting
6524	SNARF	300mm Tape Frame PI&C TF	New Standard - SPECIFICATION FOR INDICATOR PLACEMENT ZONE AND SWITCH PLACEMENT VOLUME OF 300mm TAPE FRAME FOUP LOAD PORT – Authorized new SNARF – TC Member Review took place between 4/3/2019 and 4/16/2019 before approval at the TC Chapter Meeting
6525	SNARF	Global PI&C Maintenance TF	Reapproval of SEMI E166-0814: Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard – Authorized new SNARF

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Authorized Ballots

Doc #	When	TF	Document Title/Details
6525	Cycle 5-2019	Global PIC Maintenance TF	Reapproval of SEMI E166-0814: Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard

Task Force Highlights [1/2]

- 300mm Tape Frame PI&C Task Force
 - Leaders:
 - Hayato Iwamoto / Sony Semiconductor Solutions
 - Hisashi Gotoh / Sony Semiconductor Solutions
 - Naomune Taniguchi / Tokyo Seimitsu
 - SNARFs approved
 - New Standard - SPECIFICATION FOR 300mm TAPE FRAME FOUP
 - New Standard - SPECIFICATION FOR 300mm TAPE FRAME FOUP LOAD PORT
 - New Standard - SPECIFICATION FOR FRONT OPENING INTERFACE BETWEEN 300mm TAPE FRAME FOUP AND LOAD PORT
 - New Standard - SPECIFICATION FOR BOLTS OF 300mm TAPE FRAME FOUP LOAD PORT
 - New Standard - SPECIFICATION FOR INDICATOR PLACEMENT ZONE AND SWITCH PLACEMENT VOLUME OF 300mm TAPE FRAME FOUP LOAD PORT
 - Discussion
 - End-Effector Exclusion Volume inside the FOUP to be considered

Task Force Highlights [2/2]

- Panel Level Packaging (PLP) Panel FOUP Task Force
 - Leaders
 - Shoji Komatsu / Acteon NEXT
 - John Rudolf / Intel
 - The revised SNARFs approved and Ballot submission authorized for Cycle 6 on June 25
 - 6485: New Standard: Specification for Panel FOUP For Panel Level Packaging
 - 6486: New Standard: Specification for Panel FOUP Loadport For Panel Level Packaging

Five-Year Review

Designation	Standard Title	Action By	Assigned to
SEMI E166-0814	Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard	Summer 2019	Global PIC Maintenance TF

** Nonconforming title needs to be addressed in addition to Five-Year review*

Thank you
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